

### **AMENDMENTS TO THE CLAIMS:**

1. (Previously presented) A heatsink assembly, comprising:  
a heatsink;  
a stabilization plate, being located on a bottom of the heatsink and surrounding a die of a chip and a thermal pad coupled to the heatsink, for making the thermal pad closely compact to the die of the chip when the heatsink is located on the chip, wherein a thickness of the stabilization plate is smaller than a thickness of the die; and  
an amount of paste, coated on the stabilization plate, for sticking the stabilization plate on the bottom of the heatsink.
2. (Previously presented) The heatsink stabilization plate of claim 1, wherein the stabilization plate is an n-shaped slice in a top view.
3. (Canceled)
4. (Previously presented) The heatsink stabilization plate of claim 1, wherein the stabilization plate has a fingerprint thereon after being pressed by a finger, but the fingerprint disappears right away.
5. (Previously presented) A cooling assembly, comprising:  
a stabilization plate; and  
a heatsink, stuck with the stabilization plate, wherein the heatsink comprises a right portion and a left portion respectively having a first plurality of cooling fins and a second plurality of cooling fins, and the second cooling fins are less than the first cooling fins.

Claims 6-7 (Canceled)

8. (Previously presented) The cooling assembly of claim 5, further comprising a thermal pad located under the heatsink through which heat from a socket is conducted to the heatsink.

9. (Previously presented) The cooling assembly of claim 8, wherein the stabilization plate surrounds the thermal pad for making the thermal pad closely compact to the die when the heatsink is located on the die.

10. (Previously presented) The cooling assembly of claim 5, wherein the stabilization plate has a thickness smaller than that of the die.

11. (Previously presented) The cooling assembly of claim 5, wherein the stabilization plate has a fingerprint thereon after being pressed by a finger, but the fingerprint disappears right away.

12. (Previously presented) The cooling assembly of claim 5, wherein the stabilization plate comprises two bars respectively having length of about 49.29 to about 49.31 millimeters in a top view.

13. (Previously presented) The cooling assembly of claim 5, wherein the bars respectively have width of about 9.99 to about 10.01 millimeters in a top view.

14. (Previously presented) The cooling assembly of claim 5, wherein the stabilization plate comprises a lateral bar having a length of about 48.69 millimeters to about 48.71 millimeters in a top view.

15. (Previously presented) The heatsink assembly of claim 1, wherein the stabilization plate is made from a soft and elastic material.

16. (Previously presented) The cooling assembly of claim 5, wherein the stabilization plate is made from a soft and elastic material.

17. (Previously presented) A cooling assembly for conducting the heat from a die of a chip, comprising:

a heatsink;

a thermal pad, stuck to a bottom of the heatsink; and

a stabilization plate, stuck to the bottom of the heatsink,

wherein the stabilization plate is set around and apart from the thermal pad and the die of the chip for making the thermal pad closely contact the die of the chip.